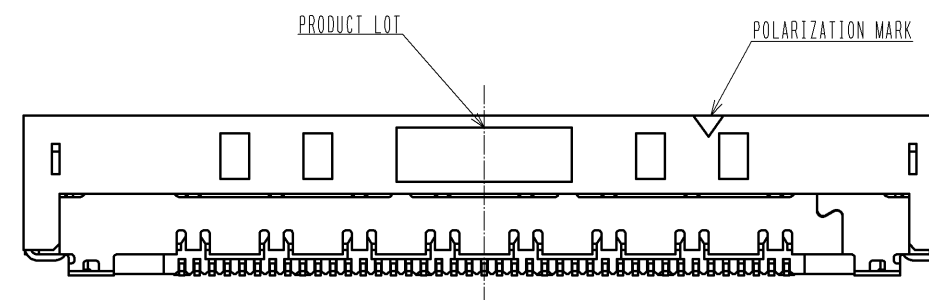
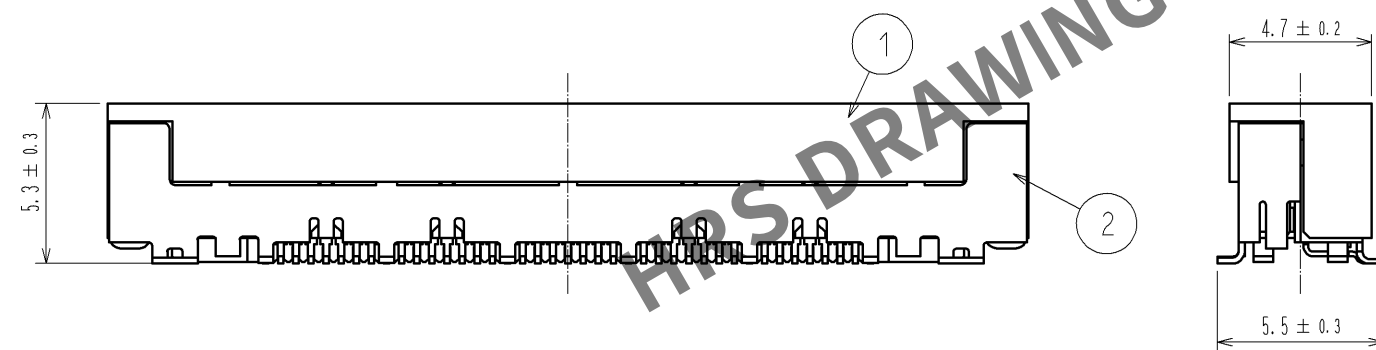
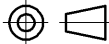




- 2  AREA OF INNER SMT LAND REQUIRES PATTERN PROHIBITION OR RESIST TREATMENT TO PREVENT THE PATTERN TOUCHING TO THE CONTACTS.
- 3 () INDICATES A REFERENCE DIMENSION.
- 4 MANUFACTURING PROCESS COULD LEAVE SCRATCH AND/OR PUNCH MARKS HAVING NO AFFECT ON THE PRODUCT PERFORMANCE.
- 5 PACKAGING FOR THIS PRODUCT APPLIES EMBOSSED CARRIER TAPE PACKAGING. SEE SHEET 2/2 FOR DETAILS.

3		PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1 μ m min.		5	PI	TAPE FOR VACUUM PICK UP				
1		PA	LEAD AREA:GOLD 0.03 μ m min.		5	PE	COVER TAPE				
			UNDER PLATING:NICKEL 1 μ m min.		4	PS	EMBOSSED CARRIER TAPE				
			BLACK. UL94V-0		2	BRASS	OVER PLATING: TIN PLATING 1 μ m min.				
							UNDER PLATING: NICKEL 2 μ m min.				
NO.		MATERIAL		FINISH , REMARKS		NO.	MATERIAL		FINISH , REMARKS		
UNITS mm				SCALE 4 : 1		COUNT 2	DESCRIPTION OF REVISIONS DIS-F-005350		DESIGNED KN. SHIBUYA	CHECKED HT. YAMAGUCHI	DATE 11.03.01
 HIROSE ELECTRIC CO., LTD.		APPROVED : HS. OKAWA		10.03.09		DRAWING NO. EDC3-330389-00					
		CHECKED : HT. YAMAGUCHI		10.03.09		PART NO. FX16M2-41S-0.5SV					
		DESIGNED : TP. MATSUMOTO		10.03.08		CODE NO. CL575-3002-6-00					
		DRAWN : TP. MATSUMOTO		10.03.08		 					

